

Data requirements for semiconductor die —

Part 2: Vocabulary

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National foreword

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Summary of pages

This document comprises a front cover, an inside front cover, pages i and ii, the ES title page, pages 2 to 14 and a back cover.

This standard has been updated (see copyright date) and may have had amendments incorporated. This will be indicated in the amendment table on the inside front cover.

This Published Document, having been prepared under the direction of the Electrotechnical Sector Committee, was published under the authority of the Standards Committee and comes into effect on 15 December 1999

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English version

Data requirements for semiconductor die Part 2: Vocabulary

This European Specification was approved by CENELEC on 1999-06-29.

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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Foreword

This European Specification has been prepared by the CENELEC BTTF 97-1, Known good die. It was submitted to the vote during the meeting of BTTF 97-1 and approved by CENELEC as ES 59008-2 on 1999-06-29.

The following dates was fixed:

- latest date by which the existence of the ES has to be announced at national level (doa) 1999-11-01

The structure of this European Specification is as follows.

ES 59008, *Data requirements for semiconductor die.*

ES 59008-1, *General requirements.*

ES 59008-2, *Vocabulary.*

ES 59008-1, *Mechanical, material and connectivity requirements.*

ES 59008-4, *Specific requirements and recommendations.*

ES 59008-4-1, *Test and quality.*

ES 59008-4-2, *Handling and storage.*

ES 59008-4-3, *Thermal.*

ES 59008-4-4, *Electrical simulation.*

ES 59008-5, *Particular requirements and recommendations for die types.*

ES 59008-5-1, *Bare die.*

ES 59008-5-2, *Bare die with added connection structures.*

ES 59008-5-3, *Minimally-packaged die.*

ES 59008-6, *Exchange data formats and data dictionary.*

ES 59008-6-1, *Data exchange — DDX file format.*

ES 59008-6-2, *Data dictionary.*

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